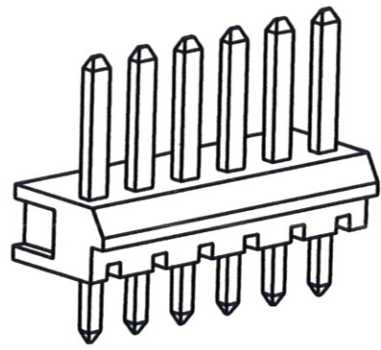
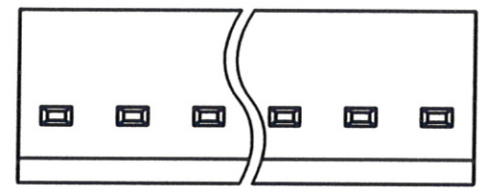


RoHS Compliant

| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|-------|
| A0 | Release To FAI20110553 | 2011.05.18 | Seven |
| A1 | Release To ECN20130303 | 2013.03.12 | Seven |



Specification
 1.Current Rating:3A AC/DC
 2.Voltage Rating:250V AC/DC
 3.Contact Resistance:10mΩ Maximum(Initial)
 20mΩ Maximum(Final)
 4.Insulation Resistance:500MΩ Minimum
 5.Dielectric Withstanding Voltage:1000V AC/Minute
 6.Operating Temperature:-25°C~+85°C

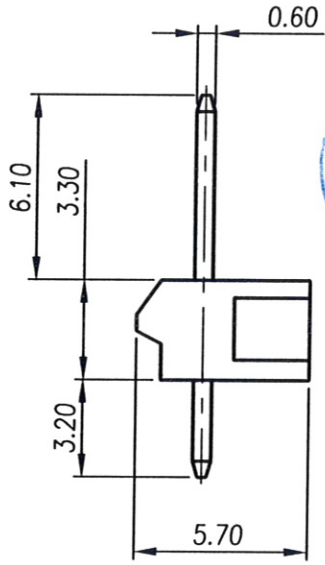
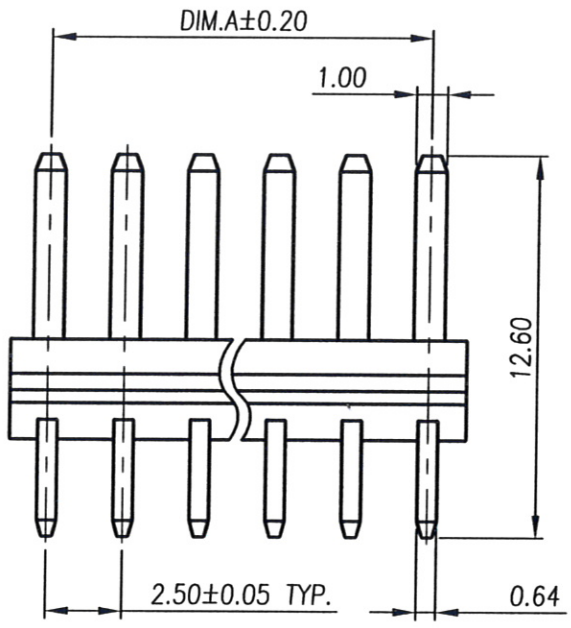
Material:
 1.Housing:High-Temp. Thermoplastic UL94V-0
 2.Contact Pin:Copper Alloy

Finish:
 1.Housing:Natural
 2.Contact Pin:Bright Tin Over Nickel

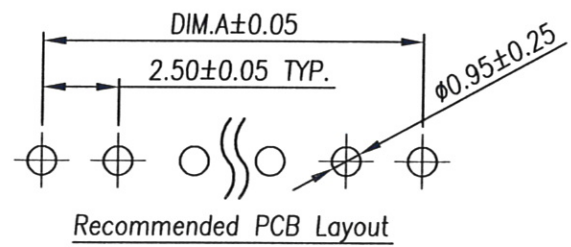
Part No.: AD05300 XX 1 1 5 G


Number Of PIN 02~20
 Packing 5:Bag

Housing Material 1:NY66 UL94V-0 Nature
 Plating 1:Bright Tin




| PIN | DIM.A | PIN | DIM.A | PIN | DIM.A |
|-----|-------|-----|-------|-----|-------|
| 02 | 2.50 | 09 | 20.00 | 16 | 37.50 |
| 03 | 5.00 | 10 | 22.50 | 17 | 40.00 |
| 04 | 7.50 | 11 | 25.00 | 18 | 42.50 |
| 05 | 10.00 | 12 | 27.50 | 19 | 45.00 |
| 06 | 12.50 | 13 | 30.00 | 20 | 47.50 |
| 07 | 15.00 | 14 | 32.50 | | |
| 08 | 17.50 | 15 | 35.00 | | |





金上達科技股份有限公司

GOLDENSUND TECHNOLOGY CO.,LTD

| | | | | | |
|--------------------------------------|------------|---------------------------------------------------------------------------------------------|--------------------------------------------|-------------------------|----------------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | PROJ.  | TITLE: Wire To Board Wafer 2.50mm 180° DIP | | |
| .x± 0.35 | x.*± 2° | APR. Jay 20130312 | PART NO. AD05300XX115G | DWG NO. AD05300XX115G | |
| .xx± 0.25 | .x*± 1° | CHK. Michelle 20130312 | UNITS: mm | CUSTOMER DRAWING | |
| .xxx± 0.15 | .xx*± 0.5° | DRA. Seven 20130212 | SIZE: A4 | SCALE 4:1 | SHEET 1 / 1 REV A1 V |